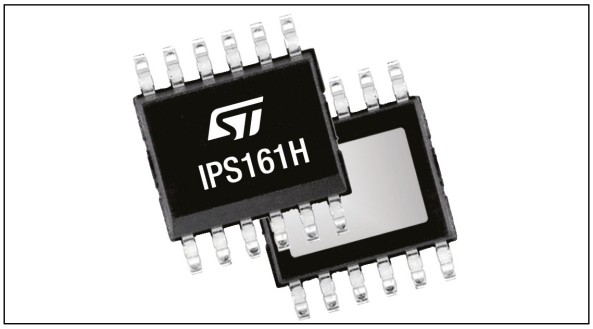
IPS161H

Single high-side switch

Datasheet - production data



Features

- $R_{DS(on)}$ = 0.060 Ω, I_{OUT} = 0.7 A, V_{CC} = 65 V
- 8 V to 60 V operating voltage range
- Minimum output current limitation: 0.7 A
- Non-dissipative short-circuit protection (cut-off)
- Programmable cut-off delay time using external capacitor
- Diagnostic signalization for: open load in off-state, cut-off and junction thermal shutdown
- Fast demagnetization of inductive load
- Ground disconnection protection
- V_{CC} disconnection protection
- Undervoltage lock-out
- Designed to meet IEC 61131-2

Applications

- Programmable logic control
- Industrial PC peripheral input/output
- Numerical control machines
- SIL applications

Description

The IPS161H is a monolithic device which can drive capacitive, resistive or inductive loads with one side connected to ground; it is specifically designed to match safety integrity level (SIL) applications.

Built-in thermal shutdown protects the chip against overtemperature and short-circuit. In order to minimize the power dissipation when the output is shorted, a non-dissipative short-circuit protection (cut-off) is implemented, it limits both the output average current value and, consequently, the device overheating. The DIAG common diagnostic pin reports the thermal shutdown, open load in off-state and cut-off.

Cut-off delay time can be programmed by an external capacitor.

Table 1. Device summary

Order code	Package	Packing
IPS161H	PowerSSO12	Tube
IPS161HTR		Tape and reel

Product label
SUSTAINABLE TECHNOLOGY

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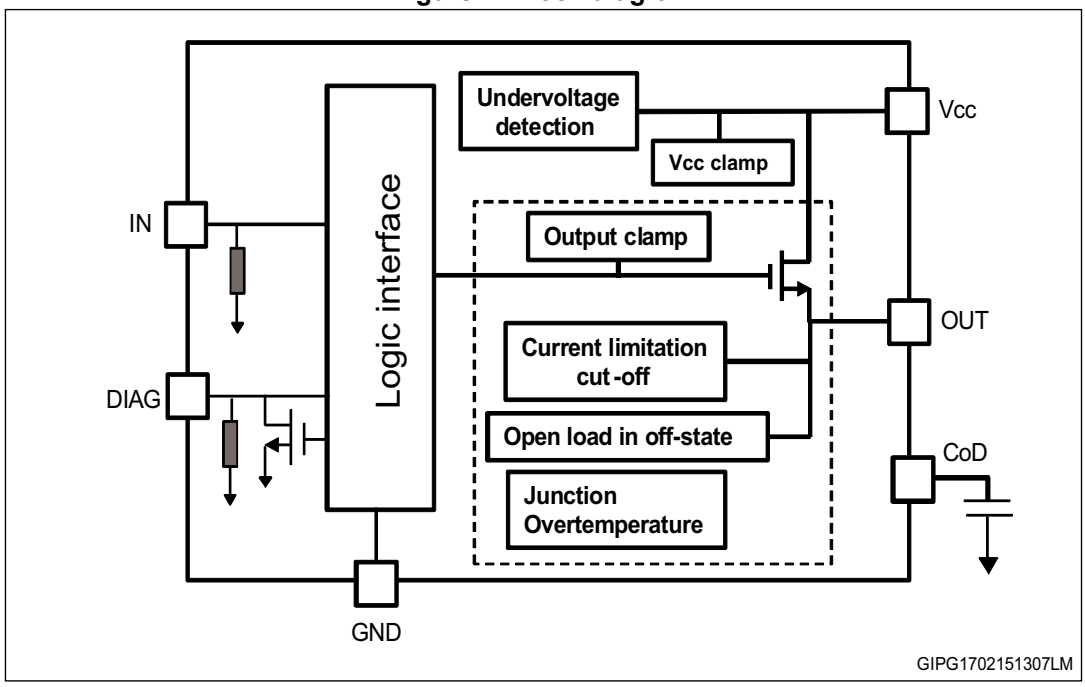
1 Block diagram

Figure 1. Block diagram



2 Pin description

Figure 2. Pin connection (top view)

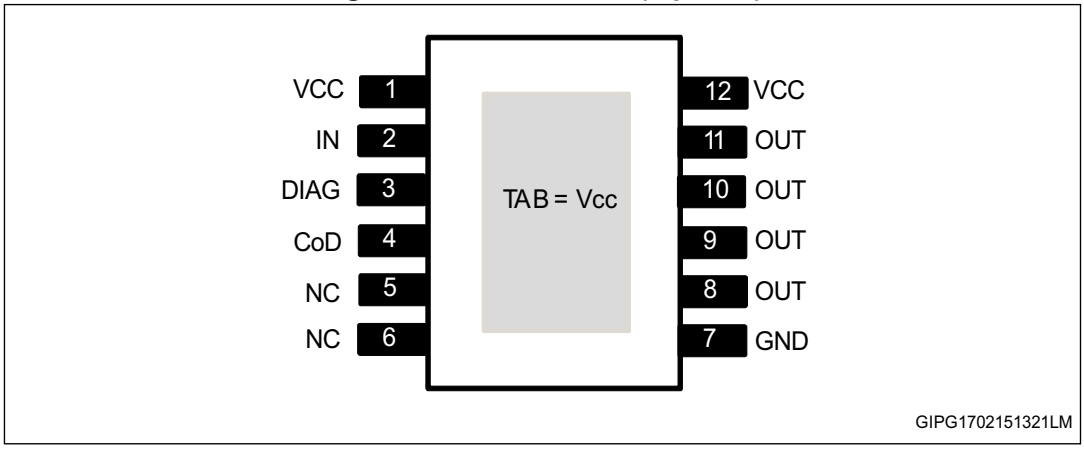


Table 2. Pin configuration

Number	Name	Function	Type
1, 12, TAB	VCC	Device supply voltage	Supply
2	IN	Channel input	Input
3	DIAG	Common diagnostic pin both for thermal shutdown, cut-off and open load	Output open drain
4	CoD	Cut-off delay pin, cannot be left floating. Connected to GND by 1 kΩ resistor to disable the cut-off function. Connect to a C_{CoD} capacitor to set the cut-off delay see *Table 9: Protection and diagnostic on page 10*.	Input
5, 6	NC	Not connected	
7	GND	Device ground	Ground
8, 9, 10, 11	OUT	Channel power stage output	Output

2.1 IN

This pin drives the output stage to pin OUT. IN pin has internal weak pull-down resistors, see *Table 8: Logic inputs on page 10*.

2.2 OUT

Output power transistor is in high-side configuration, with active clamp for fast demagnetization.

2.3 DIAG

This pin is used for diagnostic purpose and it is internally wired to an open drain transistor. The open drain transistor is turned on in case of junction thermal shutdown, cut-off, or open load in off-state.

2.4 CoD

This pin cannot be left floating and can be used to program the cut-off delay time t_{coff}, see *Table 9: Protection and diagnostic on page 10* through an external capacitor (C_{CoD}). The cut-off function can be completely disabled connecting the CoD pin to GND through 1 kΩ resistor: in this condition the output channel remains on in limitation condition, supplying the current to the load until the input is forced LOW or the thermal shutdown threshold is triggered or t_{coff} time elapses.

2.5 GND

IC ground.

2.6 VCC

IC supply voltage.

3 Absolute maximum ratings

Table 3. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CC}	Supply voltage	-0.3 to 65	V
V_{OUT}	Output channel voltage	V_{CC} - V_{clamp} to V_{CC} +0.3	V
I_{IN}	Input current	-10 to +10	mA
V_{IN}	IN voltage	V_{CC}	V
V_{COD}	Output cut-off voltage pin	5.5	V
I_{COD}	Input current on cut-off pin	-1 to +10	mA
V_{DIAG}	Fault voltage	V_{CC}	V
I_{DIAG}	Fault current	-5 to +10	mA
I_{CC}(1)	Maximum DC reverse current flowing through the IC from GND to V_{CC}	-250	mA
I_{OUT}	Output stage current	Internally limited	A
$-I_{OUT}$(1)	Maximum DC reverse current flowing through the IC from OUT to V_{CC}	5	
E_{AS}(1)	Single pulse avalanche energy (T_{AMB} = 125 °C, V_{CC} = 24 V, load = 48 Ω)	3000	mJ
P_{TOT}	Power dissipation at T_C = 25 °C(2)	Internally limited	W
T_{STG}	Storage temperature range	-55 to 150	°C
T_J	Junction temperature	-40 to 150	

1. Verified on application board with $R_{th(ja)}$ = 49 °C/W
2. $[T_{JSD(MAX)} - T_C]/ R_{th(JA)}$.

Note: Absolute maximum ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. All voltages are referenced to GND.

Table 4. Thermal data

Symbol	Parameter	Value	Unit
$R_{th(JC)}$	Thermal resistance junction-case	1	°C/W
$R_{th(JA)}$	Thermal resistance junction-ambient	49	

Note: Package mounted on a 2-layer application board with Cu thickness = 35 µm, total dissipation area = 1.5 cm^2 connected by 6 vias.

4 Electrical characteristics

8 V < V_{CC} < 60 V; -40 °C < T_J < 125 °C, unless otherwise specified.

Table 5. Supply

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{CC}	Supply voltage	-	V_{UVON}	-	60	V
V_{UVON}	Undervoltage on threshold	-	6.9	-	8	V
V_{UVOFF}	Undervoltage off threshold	-	6.5	-	7.8	V
V_{UVH}	Undervoltage hysteresis	-	0.15	0.5		V
I_S	Supply current in off-state	V_{CC} = 24 V	-	300	500	µA
		V_{CC} = 60 V	-	350	600	
	Supply current in on-state	V_{CC} = 24 V	-	1	1.4	mA
		V_{CC} = 60 V	-	1.4	2.1	
I_{LGND}	GND disconnection output current	V_{GND} = V_{IN} = V_{CC} V_{OUT} = 0 V	-	-	1	mA

Table 6. Output stage

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$R_{DS(on)}$	On-state resistance	V_{CC} = 24 V, I_{OUT} = 0.5 A at T_J = 25 °C	-	60	80	mΩ
		V_{CC} = 24 V, I_{OUT} = 0.5 A at T_J = 125 °C	-	-	120	
$V_{OUT(OFF)}$	Off-state output voltage	V_{IN} = 0 V and I_{OUT} = 0 A	-	-	2	V
$I_{OUT(OFF)}$	Off-state output current	V_{CC} = 24 V, V_{IN} = 0 V, V_{OUT} = 0 V	-	-	3	µA
		V_{CC} = 60 V, V_{IN} = 0 V, V_{OUT} = 0 V	-	-	10	
$I_{OUT(OFF-min)}$	Off-state output current	V_{IN} = 0 V, V_{OUT} = 4 V	-35	-	0	

Table 7. Switching (V_{CC} = 24 V; -40 °C < TJ < 125 °C, R_{LOAD} = 48 Ω)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t_r	Rise time	I_{OUT} = 0.5 A *Figure 3*	-	10	-	µs
t_f	Fall time		-	10	-	
$t_{PD(H-L)}$	Propagation delay time off		-	20	-	
$t_{PD(L-H)}$	Propagation delay time on		-	30	-	

Figure 3. Timing in normal operation

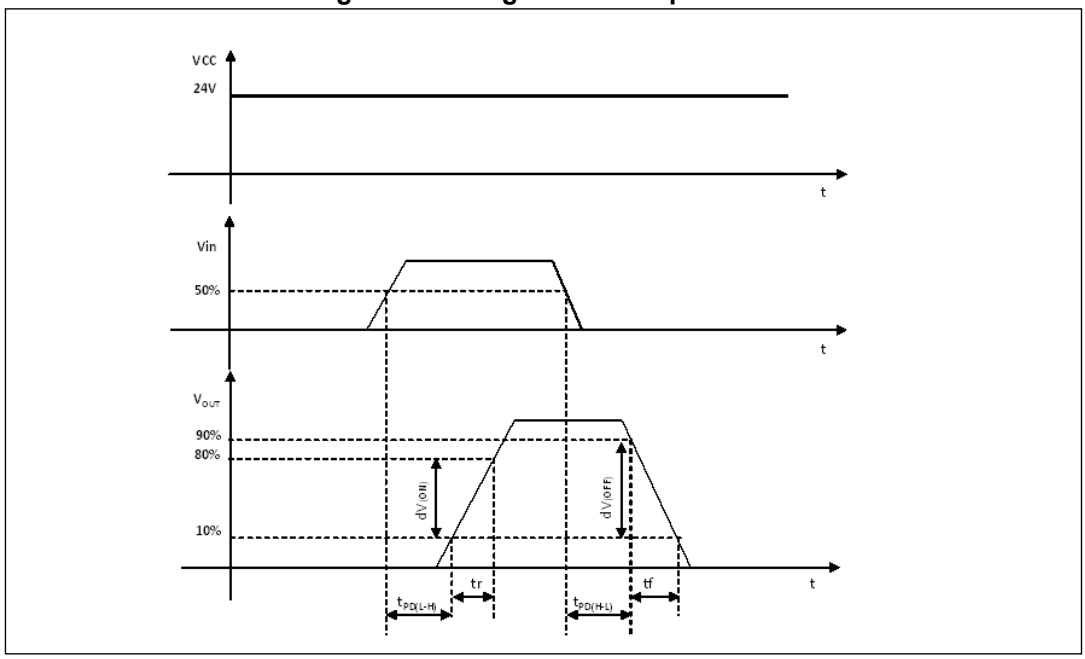


Table 8. Logic inputs

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{IL}	Input low level voltage	-	-	-	0.8	V
V_{IH}	Input high level voltage	-	2.2	-	-	
$V_{I(HYST)}$	Input hysteresis voltage	-	-	0.4	-	
I_{IN}	Input current	V_{CC} = V_{IN} = 36 V	-	-	200	µA
		V_{CC} = V_{IN} = 60 V	-	-	550	

Table 9. Protection and diagnostic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{clamp}	V_{CC} active clamp	I_{CC} = 10 mA	65.5	68.5	71.5	V
V_{demag}	Demagnetization voltage	I_{OUT} = 0.5 A; load = 1 mH	V_{CC} - 71.5	V_{CC} - 68.5	V_{CC} - 68.5	
V_{OLoff}	Open load (off- state) or short to V_{CC} detection threshold	-	2	-	4	
t_{BKT}	Open load blanking time	-	-	-	200	µs
V_{DIAG}	Voltage drop on DIAG	I_{DIAG} = 4 mA	-	-	1	V
I_{DIAG}	DIAG pin leakage current	$V_{CC} \leq$ 36 V	-	-	110	µA
		36 V < $V_{CC} \leq$ 60 V	-	-	180	
I_{LIM}	Output current limitation	$V_{CC} \leq$ 32 V, $R_{LOAD} \leq$ 10 mΩ	0.7	-	1.7	A

Table 9. Protection and diagnostic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t_{coff}	Cut-off current delay time	Programmable by the external capacitor on CoD pin. Cut-off is disabled when CoD pin is connected to GND through 1 kΩ resistor. $T_J < T_{JSD}$	50 x C_{COD} [nf] ± 35%(1)			µs
t_{res}	Output stage restart delay time	$T_J < T_{JSD}$	32 x t_{coff} [µs] ± 40%			
T_{JSD}	Junction temperature shutdown	-	150	170	190	°C
T_{JHYST}	Junction temperature thermal hysteresis	-	-	15	-	

1. The formula is guaranteed in the range 10 nF ≤ C_{COD} ≤ 100 nF.

5 Output logic

Table 10. Output stage truth table

Operation	IN	OUT	DIAG
Normal	L H	L H	H H
Cut-off	L H	L L	L L
Overtemperature	L H	L L	L L
Open load	L H	H (external pull-up resistor is used) H	L (external pull-up resistor is used) H
UVLO	X X	L L	X X

6 Protection and diagnostic

The IC integrates several protections to ease the design of a robust application.

6.1 Undervoltage lock-out

The device turns off if the supply voltage falls below the turn-off threshold [$V_{UV(off)}$]. Normal operation restarts after V_{CC} exceeds the turn-on threshold [$V_{UV(on)}$]. Turn-on and turn-off thresholds are defined in *Table 5: Supply on page 9*.

6.2 Overtemperature

The output stage turns off when its internal junction temperature (T_J) exceeds the shutdown threshold T_{JSD}. Normal operation restarts when T_J comes back below the reset threshold (T_{JSD} - T_{JHYST}), see *Table 9: Protection and diagnostic*. The internal fault signal is set when the channel is off due to thermal protection and it is reset when the junction triggers the reset threshold. This same behavior is reported on DIAG pin.

6.3 Cut-off

The IC can limit the output current at the power stage by its embedded output current limitation circuit.

This circuit continuously monitors the output current and, when load is increasing, at the triggering of its activation threshold ($1.8A_{TYP}$) it starts limiting to ILIM limitation level (see *Table 8*): while current limitation is active the IC enters a high dissipation status.

The IPS161H implements the cut-off feature which limits the duration of the current limitation condition.

The duration of the current limitation condition (T_{coff}) can be set by a capacitor (C_{CoD}) placed between CoD and GND pins. The design rule for C_{CoD} is:

$t_{coff[\mu s]} \pm 35\% = 50 \times C_{cod[nF]}$

The drift of +/-35% is guaranteed in the range of 10 nF < C_{cod} < 100 nF; lower capacitance than 10 nF can be used.

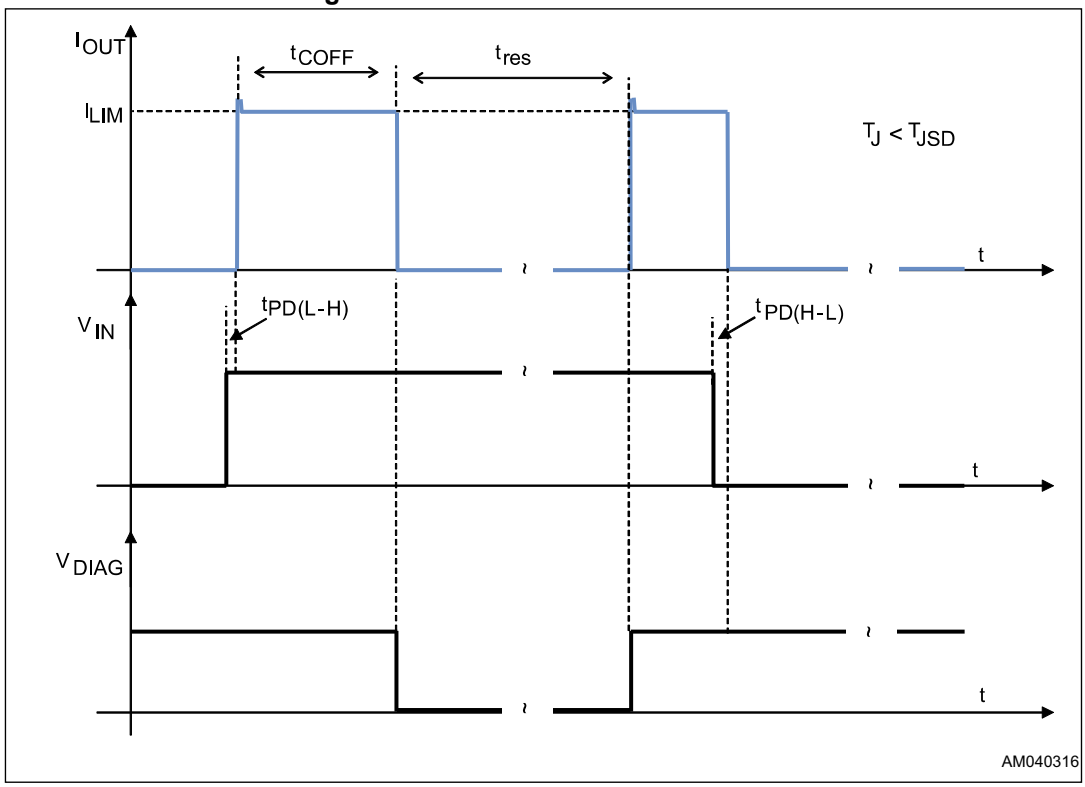
If I_{LIM} threshold is triggered, the output stage remains in the current limitation condition

($I_{OUT} = I_{LIM}$) no longer than t_{coff}. If t_{coff} elapses, the output stage turns off and restarts after the t_{res} restart time.

Thermal shutdown protection has higher priority than cut-off:

- IC is forced off if T_{JSD} is triggered before t_{coff} elapses
- If T_{JSD} is triggered, IC is maintained off even after the t_{res} has elapsed and until the T_J decreases below T_{JSD} - T_{JHYST}

Figure 4. Current limitation and cut-off



The fault condition is reported on the DIAG pin. The internal cut-off flag signal is latched at output switch-off and released after the time t_{res}, the same behavior is reported on DIAG pin.

The status of the DIAG is independent on the IN pin status.

If CoD pin is connected to GND through 1 kΩ resistor (cut-off feature disabled), when the output channel triggers the limitation threshold, it remains on, in current limitation condition, until the input becomes LOW or the thermal protection threshold is triggered.

In case of low ambient temperature conditions (T_{AMB} < -20 °C) and high supply voltage (V_{CC} > 36 V) the cut-off function needs activating in order to avoid IC permanent damages. The following table reports the suggested cut-off delay for the different operating voltage.

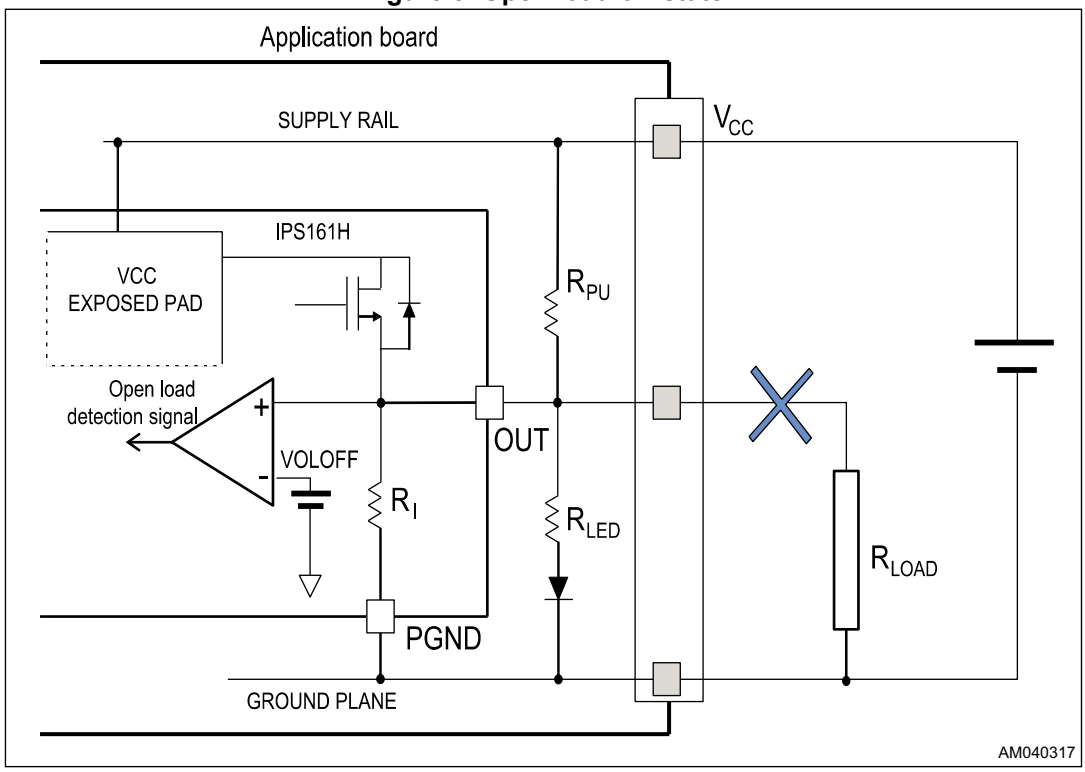
Table 11. Minimum cut-off delay for T_{AMB} less than -20 °C

V_{CC} [V]	Cut-off delay [µs]	Cut-off capacitance [nF]
36-48	100	2.2
48-60	50	1

6.4 Open load in off-state

The IPS161H provides the open load detection feature which detects if the load is disconnected from the OUT pin. This feature can be activated by a resistor (R_{PU}) between OUT and VCC pins.

Figure 5. Open load off-state



In case of wire break and during the OFF state (IN = low), the output voltage V_{OUT} rises according to the partitioning between the external pull-up resistor and the internal impedance of the IC (130 kΩ < RI < 360 kΩ).

The effect of the LED (if any) on the output pin has to be considered as well. In case of wire break and during the ON state (IN = high), the output voltage V_{OUT} is pulled up to V_{CC} by the low resistive integrated switch. If the load is not connected, in order to guarantee the correct open load signalization it must result:

Equation 1

$V_{OUT} > V_{OLoff(max)}$

Referring to the circuit in *Figure 5*:

Equation 2

$$V_{OUT} = V_{CC} - R_{PU} \times I_{PU} = V_{CC} - R_{PU} \times (I_{RI} + I_{LED} + I_{RL})$$

therefore:

Equation 3

$$R_{PU} < \frac{V_{CC(min)} - V_{OLoff(max)}}{\left(\frac{V_{OLoff(max)}}{R_{I(min)}} + \frac{V_{OLoff(max)} - V_{LED}}{R_{LED}}\right)}$$

If the load is connected, in order to avoid any false signalization of the open load, it must result as follows:

Equation 4

$V_{OUT} < V_{OLoff(min)}$

By taking into account the circuit in *Figure 5*:

Equation 5

$$V_{OUT} = V_{CC} - R_{PU} \times I_{PU} = V_{CC} - R_{PU} \times \left(\frac{V_{OUT}}{R_I} + \frac{V_{OUT} - V_{LED}}{R_{LED}} + \frac{V_{OUT}}{R_L}\right)$$

so:

Equation 6

$$R_{PU} > \frac{V_{CC(max)} - V_{OLoff(min)}}{\left(\frac{V_{OLoff(min)}}{R_{I(max)}} + \frac{V_{OLoff(min)} - V_{LED}}{R_{LED}} + \frac{V_{OLoff(min)}}{R_L}\right)}$$

The fault condition is reported on the DIAG pin and the fault reset occurs when load is reconnected.

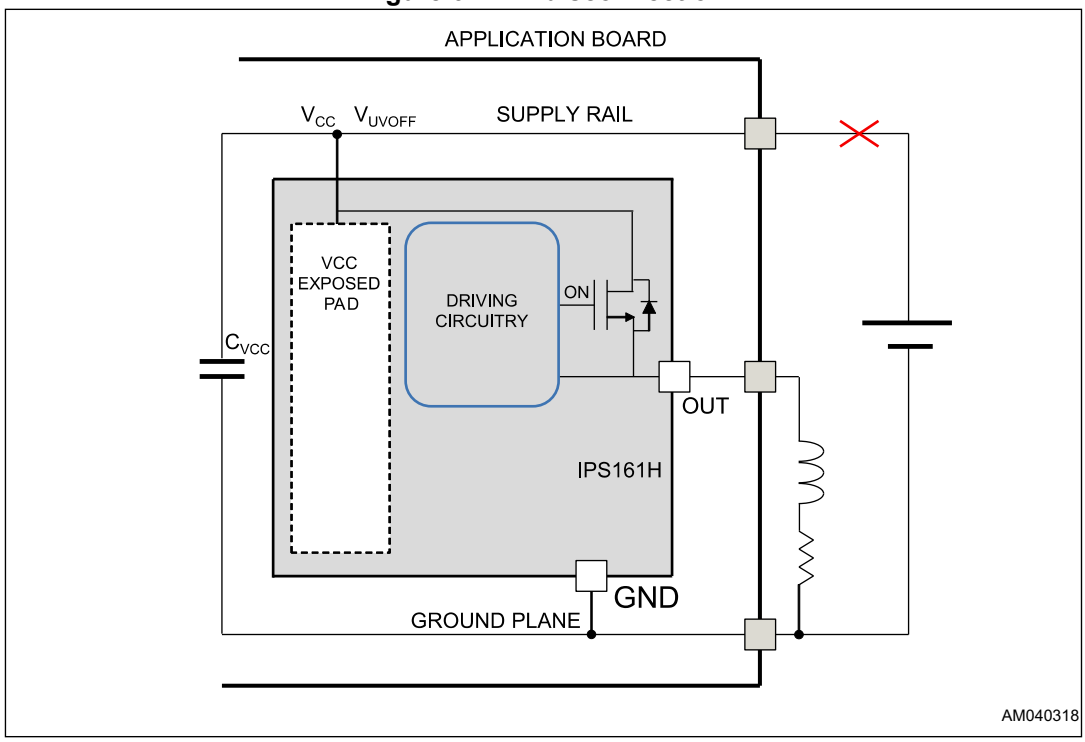
If the channel is switched on by IN pin, the fault condition is no longer detected.

When inductive load is driven, some ringing of the output voltage may be observed at the end of the demagnetization. In fact, the load is completely demagnetized when I_{LOAD} = 0 A and the OUT pin remains floating until next turn-on. In order to avoid a fake signalization of the open load event driving inductive loads, the open load signal is masked for t_{BKT}. So, the open load is reported on the DIAG pin with a delay of t_{BKT} and if the open load event is triggered for more than t_{BKT}.

6.5 VCC disconnection protection

The IC is protected despite the V_{CC} disconnection event. This event is intended as the disconnection of the V_{CC} wire from the application board, see *Figure 6*. When this condition happens, the IC continues working normally until the voltage on the V_{CC} pin is ≥ $V_{UV(OFF)}$. Once the V_{UVOFF} is triggered, the output channel is turned off independently on the input status. In case of inductive load, if the V_{CC} is disconnected while the output channel is still active, the IC allows the discharge of the energy still stored in the inductor through the integrated power switch.

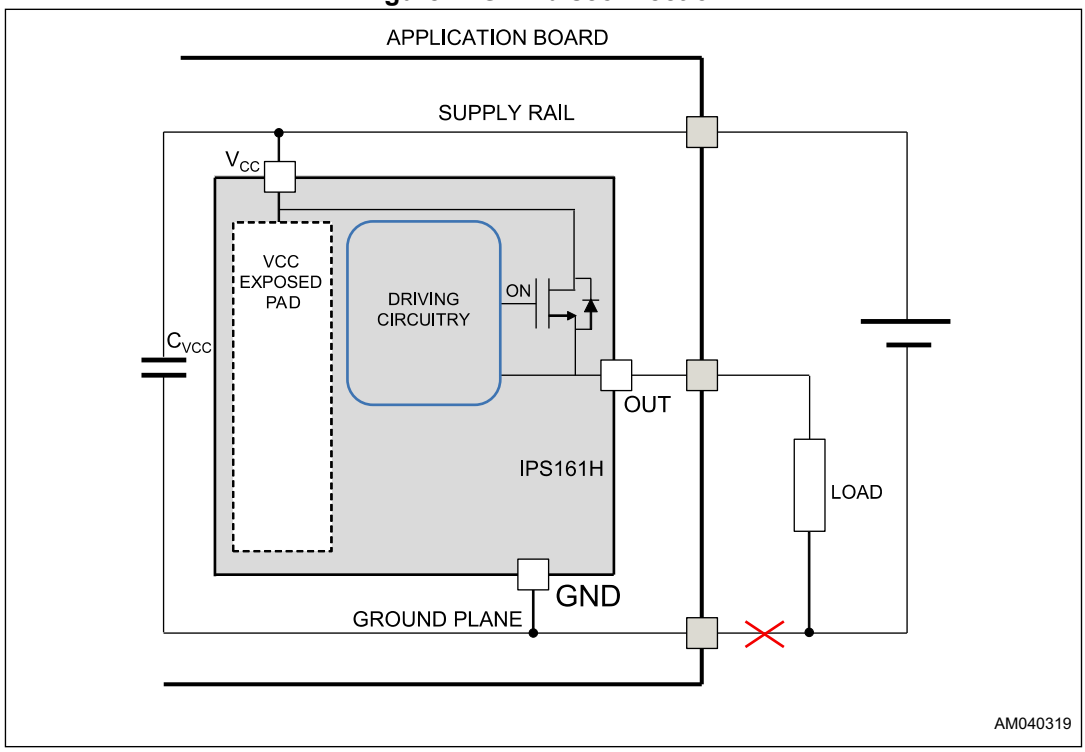
Figure 6. VCC disconnection



6.6 GND disconnection protection

GND disconnection is intended as the disconnection event of the application ground, see *Figure 7*. When this event happens, the IC continues working normally until the voltage between V_{CC} and GND pins of the IC results $\geq V_{UVOFF}$. The voltage on GND pin of the IC rises up to the supply rail voltage level. In case of GND disconnection event, a current (I_{LGND}) flows through OUT pin. *Table 8: Logic inputs on page 10* reports $I_{OUT} = I_{LGND}$ for the worst case of GND disconnection event in case of output shorted to ground.

Figure 7. GND disconnection



7 Active clamp

Active clamp is also known as fast demagnetization of inductive loads or fast current decay. When a high-side driver turns off an inductance, an undervoltage is detected on output.

The OUT pin is pulled down to V_{demag}. The conduction state is modulated by an internal circuitry in order to keep the OUT pin voltage at about V_{demag} until the load energy has been dissipated. The energy is dissipated both in IC internal switch and in load resistance.

Figure 8. Active clamp equivalent principle schematic

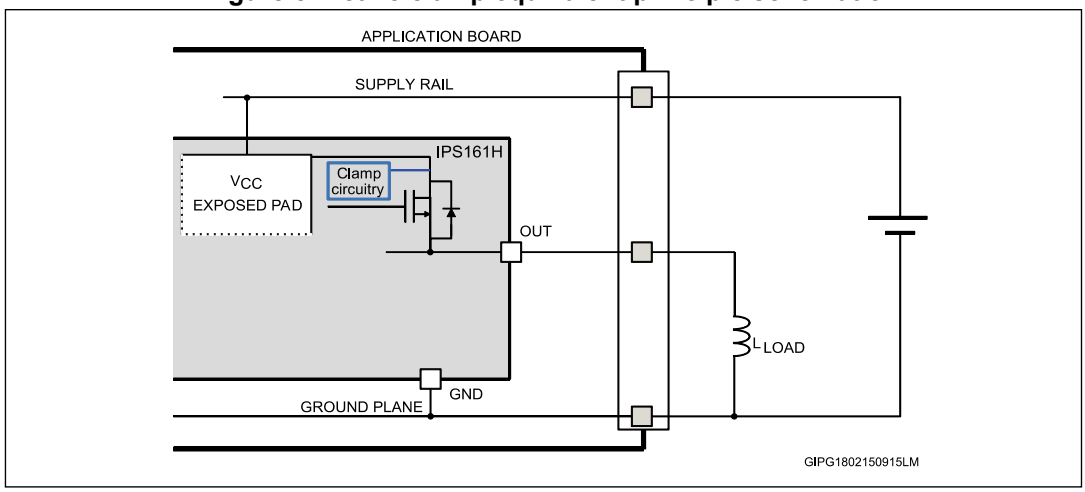
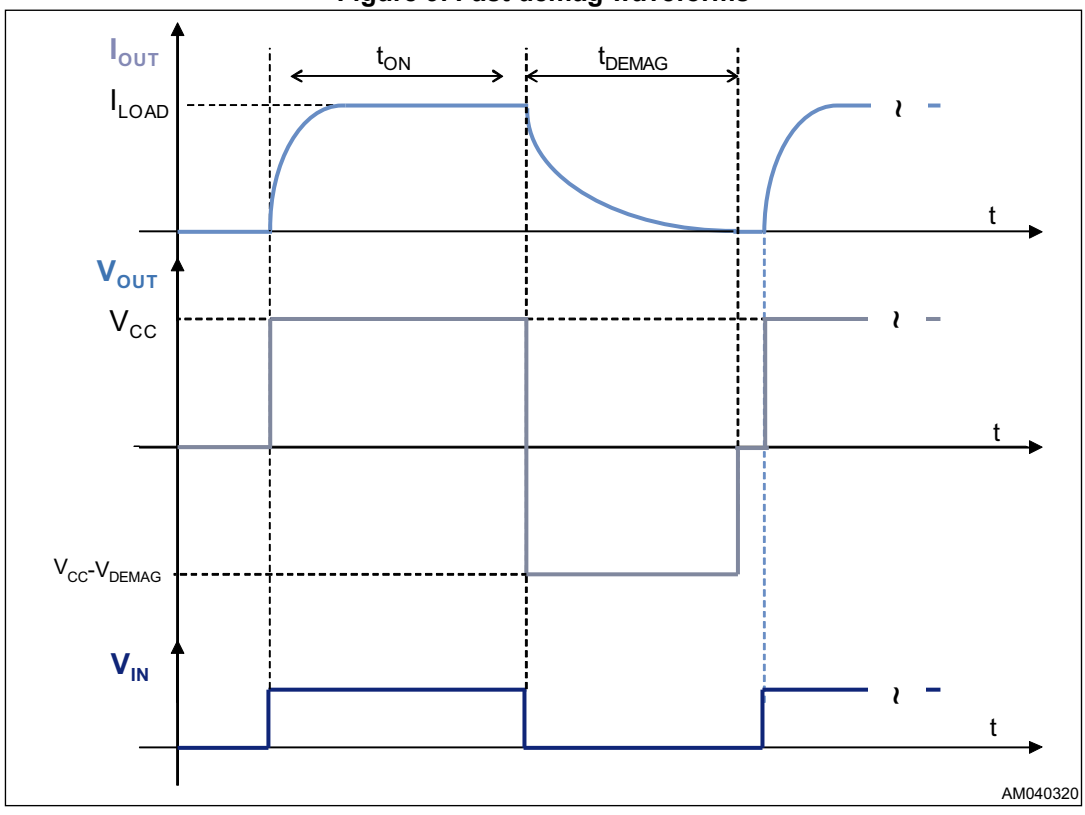
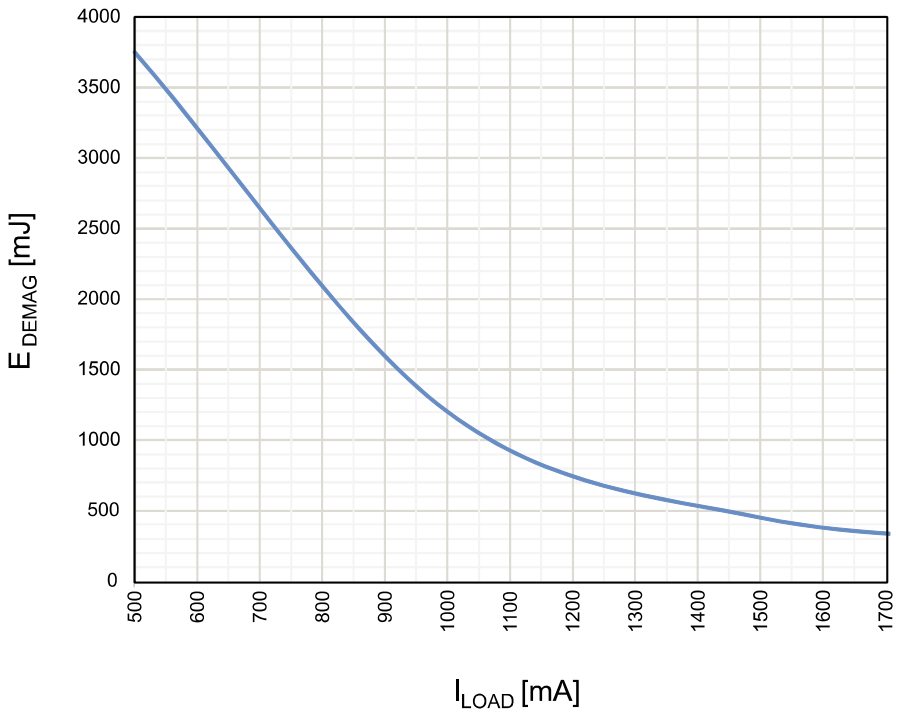


Figure 9. Fast demag waveforms



The demagnetization of inductive load causes a huge electrical and thermal stress to the IC. The curve plotted below shows the maximum demagnetization energy that the IC can support in a single demagnetization pulse with V_{CC} = 24 V and T_{AMB} = 125 °C. If higher demagnetization energy is required then an external free-wheeling Schottky diode has to be connected between OUT (cathode) and GND (anode) pins. Note that in this case the fast demagnetization is inhibited.

Figure 10. Typical demagnetization energy (single pulse) at V_{CC} = 24 V and T_{AMB} = 125 °C



8 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK® is an ST trademark.

8.1 PowerSSO12 package information

Figure 11. PowerSSO12 package outline

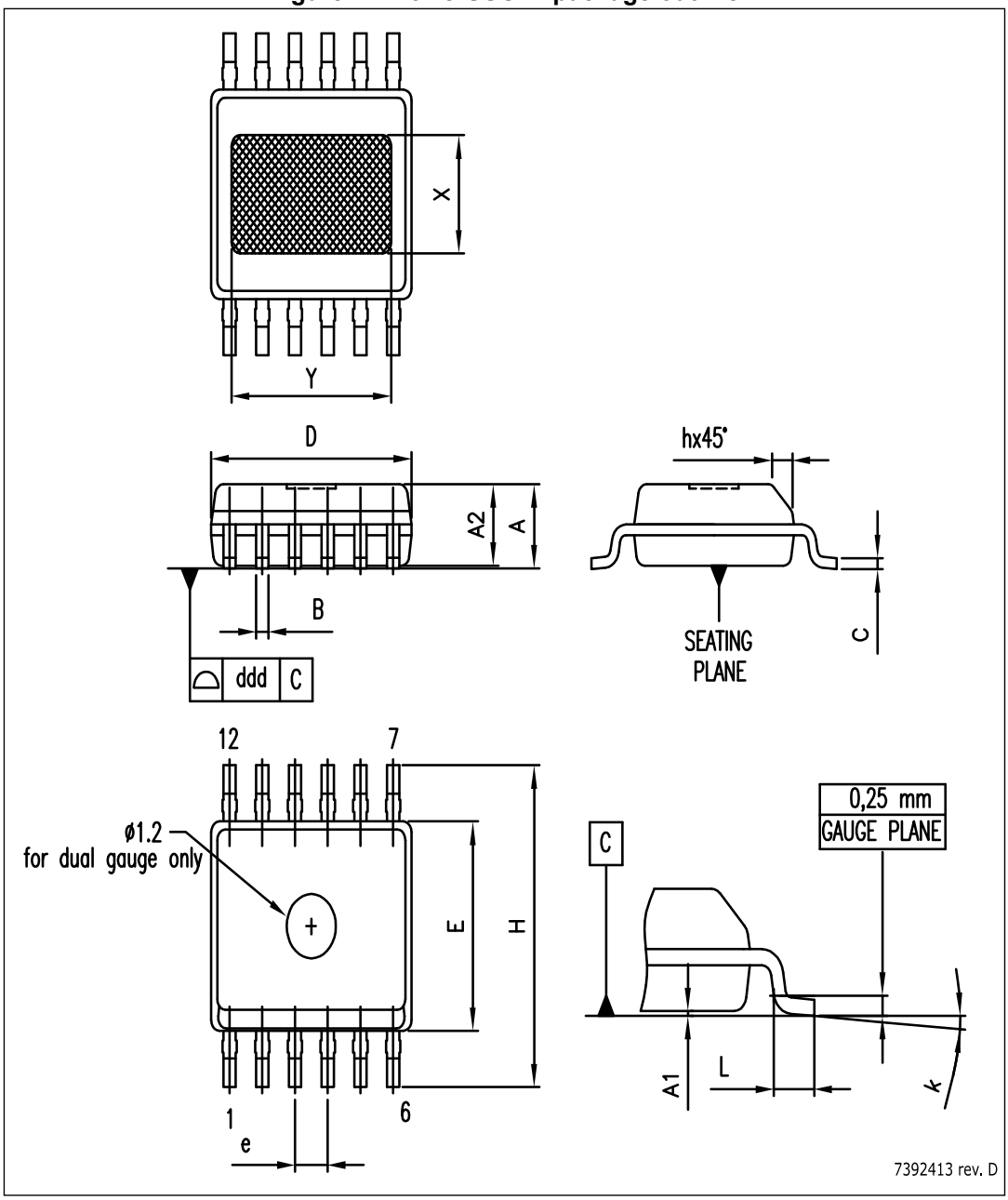


Table 12. PowerSSO12 package mechanical data

Symbol	Dimensions (mm)		
	Min.	Typ.	Max.
A	1.250	-	1.700
A1	0.000	-	0.100
A2	1.100	-	1.600
B	0.230	-	0.410
C	0.190	-	0.250
D(1)	4.800	-	5.000
E	3.800	-	4.000
e	-	0.800	-
H	5.800	-	6.200
h	0.250	-	0.55
L	0.400	-	1.270
k	0d	-	8d
X	1.900	-	2.500
Y	3.600	-	4.200
ddd		-	0.100

1. Dimension D doesn't include mold flash protrusions or gate burrs. Mold flash protrusions or gate burrs don't exceed 0.15 mm in total both side.

Figure 12. PowerSSO12 recommended footprint

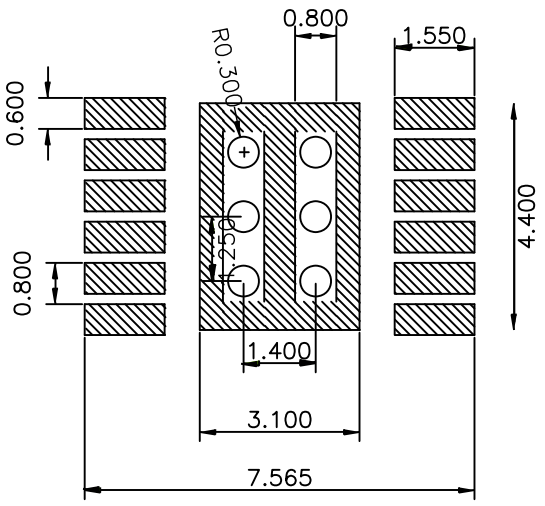
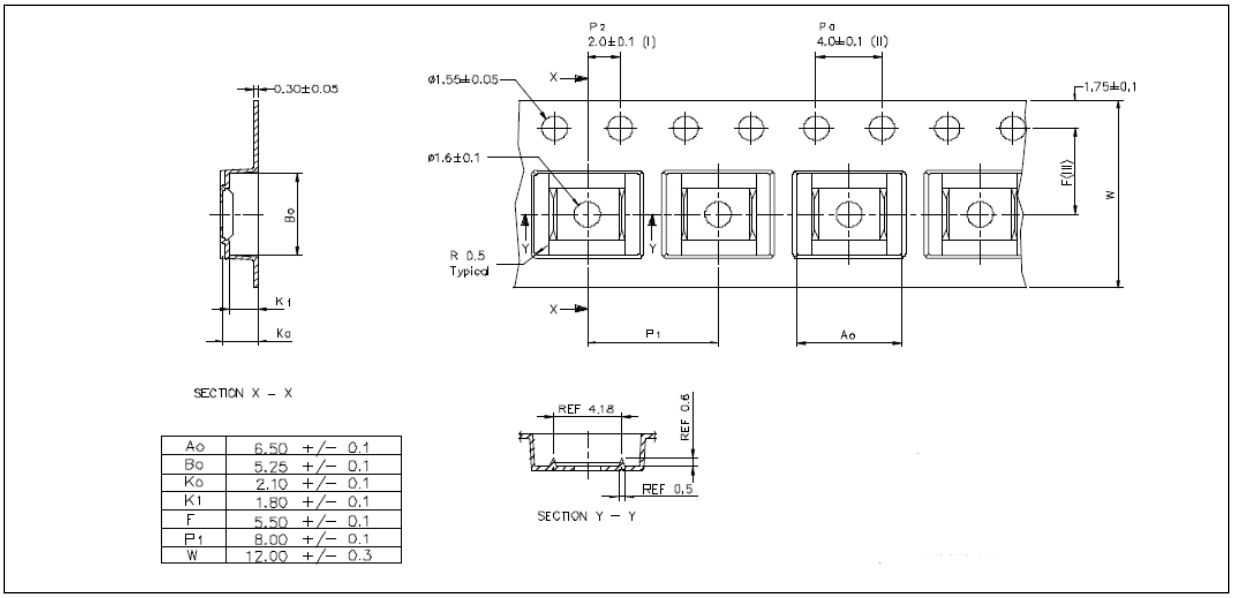
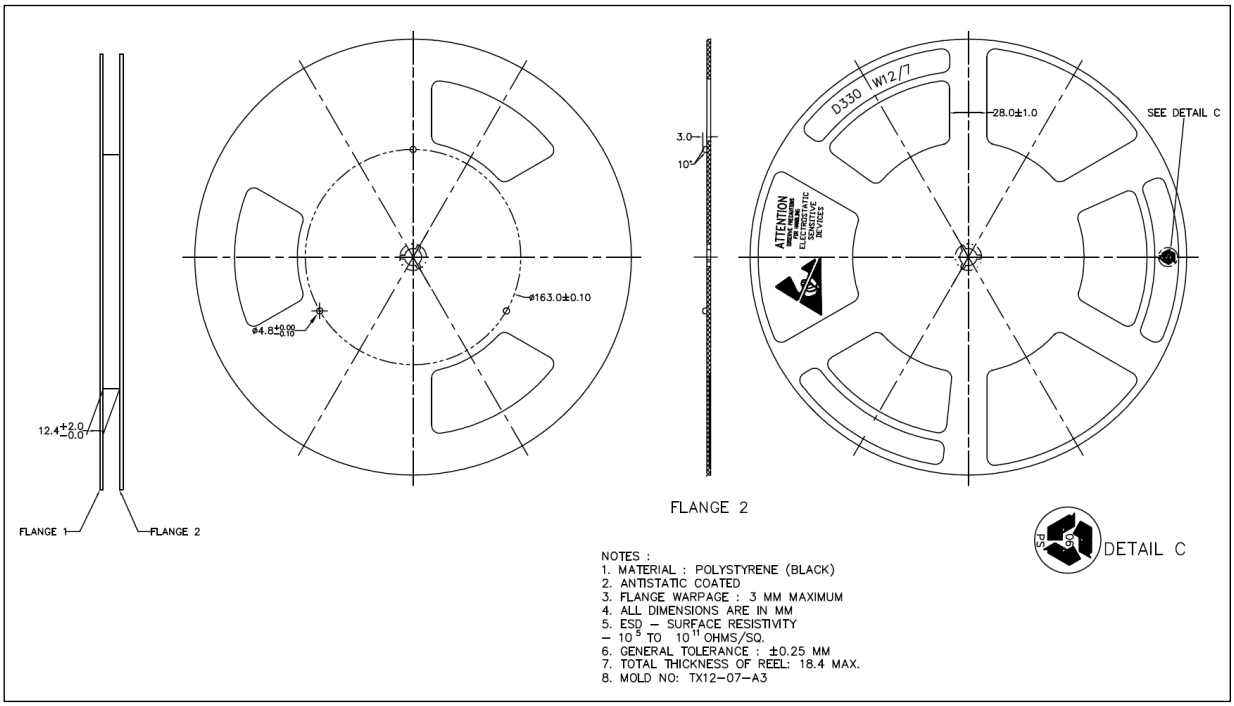


Figure 13. PowerSSO12 tape packing information [mm]



Ao	6.50 +/– 0.1
Bo	5.25 +/– 0.1
Ko	2.10 +/– 0.1
K1	1.80 +/– 0.1
F	5.50 +/– 0.1
P1	8.00 +/– 0.1
W	12.00 +/– 0.3

Figure 14. PowerSSO12 reel packing information [mm]



9 Revision history

Table 13. Document revision history

Date	Revision	Changes
10-Jun-2016	1	Initial release.
04-Oct-2016	2	Datasheet promoted from preliminary to production data.
22-Mar-2018	3	Updated *Table 3: Absolute maximum ratings on page 8* (updated E_{AS} parameter and value). Minor modifications throughout document.
13-Dec-2018	4	Added *Figure 13* and *14*, amended *Table 12*, updated *Section 4* and *Section 6.3*. Changed Package image on cover page.
16-Sept-2019	5	Small change to *Table 5*.

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